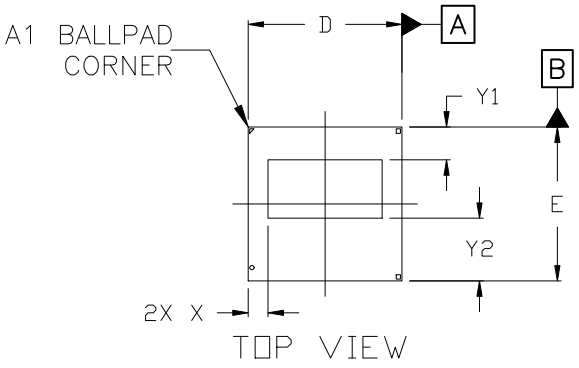
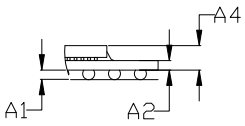
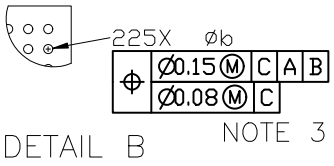
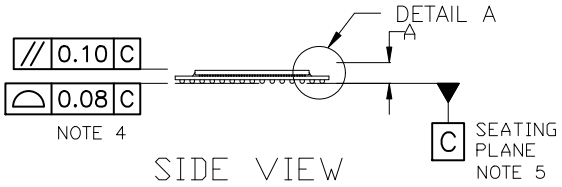
FCBGA225 10x10x0.95
CASE 489BJ
ISSUE O

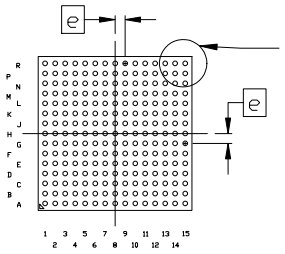
DATE 24 JUL 2019







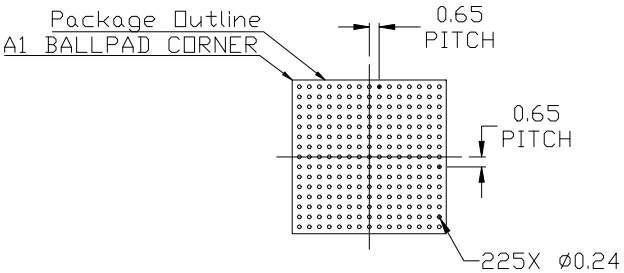




NOTES:

1. DIMENSIONING AND TOLERANCING PER. ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

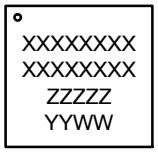
	MILLIMETERS		
DIM	MIN.	NOM.	MAX.
A	0.77	0.86	0.95
A1	0.19	0.24	0.29
A2		0.24 REF	
A4	0.58	0.62	0.66
b	0.25	0.30	0.35
D	9.90	10.00	10.10
E	9.90	10.00	10.10
e		0.65 BSC	
X		1.29 REF	
Y1		2.13 REF	
Y2		4.08 REF	



RECOMMENDED
MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
ZZZ = Assembly Lot Code
YY = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	**FCBGA225 10x10x0.95**		**PAGE 1 OF 1**